

TFT DISPLAY SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司



CUSTOMER



WEB: https://www.winstar.com.tw E-mail: sales@winstar.com.tw

SPECIFICATION

COSTOMER.		
MODULE NO.:	WFN0128A2T	OYADNNOOO
APPROVED BY:		
(FOR CUS <mark>TO</mark> MER USE ONL	Y)	
	PCB VERSION:	DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
			葉虹蘭
ISSUED DATE:	2025/07/01		•

TFT Display Inspection Specification: https://www.winstar.com.tw/technology/download.html
Precaution in use of TFT module: https://www.winstar.com.tw/technology/download/declaration.html

Wi 華	nstar Displag 菱光電股份有限	y Co., LT 公司	D	MODLE NO :
REC	ORDS OF REV	ISION		DOC. FIRST ISSUE
VERSION	DATE	REVISED PAGE NO.	SU	MMARY
0	2025/05/08		Fi	rst issue
A	2025/07/01			odify Active area and TFT
			Dı	river IC



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1.Module Classification Information

W	F	N	0128	A2	T	0Y	A	D	N	N	0	00
1	2	3	4	(5)	6	7	8	9	10	(11)	(12)	(13)

①	Brand : WINSTAR I	DISPLAY	CORPOR	RATIO	N									
2	Display Type : F→1	ГFT Type	, J→Custo	om TF	T									
3	N: Normal E : EF	D N	√I : MIP											
4	Display Size : 1.28'	TFT												
(5)	Model serials no.													
		F:	CCFL, Wh	nite			Т	-:	LED, V	Vhite				
6	Backlight Type:	s:	LED, High	Light	White		Z	<u> </u>	Nichia	LED	, White			
		N: '	With out E	acklig	jht		Α	١:	Front l	₋ight				
			ating erature	Nor	mal ter	nperat	ure		s	uper	Wide te	emperatur	e	
		LCD	tape	Т	N	IPS	VA				TN	•	IPS	VA
		ļ	angle	6H	12H	0			SH 12	!H	O-Film	OD-Film		
	LCD Polarize	ļ	ctive	AA	-	-	AT		AN -		-	-	AW	AV
		ļ	lective	0B	0E	-	02)M 0		-	-	80	04
7		Type/ Temperature Transmissive OC OF OA OT ON OQ OR OS OW OV range/ Gray Scale Operating												
	range/ Gray Scale	Uper Tempe						Wic	de temp	eratı	ıre			
	Inversion Direction	} -	tape					-	TN					
		<u></u>	angle	6H	12H	2H	3H	S	9H O-I	Film	OD-Filn	n All View	IPS	VA
		Refle	ctive	AG	AJ	AB	-		-	-	-	05	ΑY	AX
		Transf	lective	0H	0K	-	0G	C)D 0	U	\-	-	07	03
		Transn	nissive	01	0L	-	-		- C	Z	OJ	<u> </u>	0Y	0X
	A: TFT LCD						(3:	TFT+ S	Screv	v h <mark>oles</mark>			
	B: TFT+ Screw	holes+ <mark>C</mark>	ontrol boa	rd			4	┨:	TFT+ [)/V b	oard			
8	C: TFT+ <mark>S</mark> crew	holes + A	√D boar <mark>d</mark>					l :	TFT+ S	Screv	v holes +	·D/V board	d	
0	D: TFT+ Screw	holes + A	√D board	+ Cor	ntrol bo	ard	,	J :	TFT+ F	Powe	r board			
	E: TFT+ Screw	holes + F	ower boa	rd			Z	Z :	TFT+ F	Powe	r board	(Embedde	d)	
	F: TFT+ Contro	board												
	A:Analog	B: 6-bit	s parallel	D:	Digita		***************************************	••••••	Е	∶e□)P			
9	L:LVDS	M : MIP		s:	SPI									
	Interface:			<u> </u>					<u></u>					
10	A: 8Bit		B:16Bit	E	E∶eDF) H	∣:HE	MI	I : I20	C Inte	erface N	√I∶MIPI		
	N : Without Contro	l board	P : DP	F	R:RS2	232 S	: SP	1	U : U	SB				
	TS:									_	O			
	A: CTP + Optica			B:	CTP +						CTP			
_	D: CTP + USB +	···········		E:		Optic						ptical bon		
11)	H: CTP + Only (sensor-¿		J:			G-ser	nsor	r + USB			Hover Tou	ch	
	N: Without TS			Q:	in-cell						on-cell			
	T: RTP			U:	CG					۷:	in-cell -	+ CG		
	W: on-cell + CG													
12	Version:													
(13)	Serial No.: Serial nu	ımber (00	0~99)							_				
4.0														
	•													

2.Summary

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This module is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 1.28" TFT-LCD contains 240x240 pixels, and can display up to 65K/262K colors.



3.General Specifications

Item	Dimension	Unit	
Size	1.28	inch	
Dot Matrix	240 x RGB x 240 (TFT)	dots	
Module dimension	35.6 x 37.74 x 1.48	mm	
Active area	32.4 x 32.4	mm	
Pixel pitch	0.135 X 0.135	mm	
LCD type TFT, Normally Black, Transmissive			
Viewing Angle	85/85/85		
TFT Interface	8/9/16/18bit MCU 3/4SPI+16/18BIT RGB 3/4 SERIAL		
Backlight Type	LED ,Normally White		
TFT Driver IC	GC9A01 or Equivalent		
With /Without TP	Without TP	O	
Surface	Anti-Glare	0,	

^{*}Color tone slight changed by temperature and driving voltage.

4.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	TOP	-20	_	+70	°C
Storage Temperature	TST	-30	_	+80	°C

Note: Device is subject to be damaged permanently if stresses beyond those absolute maximum ratings listed above

1. Temp. \leq 60°C, 90% RH MAX. Temp. > 60°C, Absolute humidity shall be less than 90% RH at 60°C



5.Electrical Characteristics

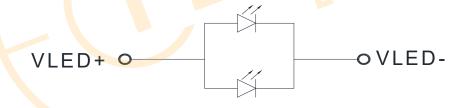
5.1. Operating conditions

Item	Symbol	Min.	Тур.	Max.	Unit	Note
Digital Supply Voltage	VCC	2.5	2.8	3.3	V	
Digital interface supple Voltage	IOVCC	1.65	2.8	3.3	V	
Normal mode Current consumption	ICC		6	12	mA	
Loyel input veltage	VIH	0.7*IOVCC		IOVCC	V	
Level input voltage	VIL	GND		0.3*IOVCC	V	
Level entent veltere	VOH	0.8*IOVCC		IOVCC	V	
Level output voltage	VOL	GND		0.2*IOVCC	V	

5.2. LED driving conditions

Item	Symbol	Min.	Тур.	Max.	Unit	Note
LED current	-	-	40	-	mA	-
LED voltage	VLED+	2.8	3.0	3.2	V	Note 1
LED Life Time	-	50000		-	H r	Note 2,3,4

Note 1 : There are 1 Groups LED



CIRCUIT DIAGRAM

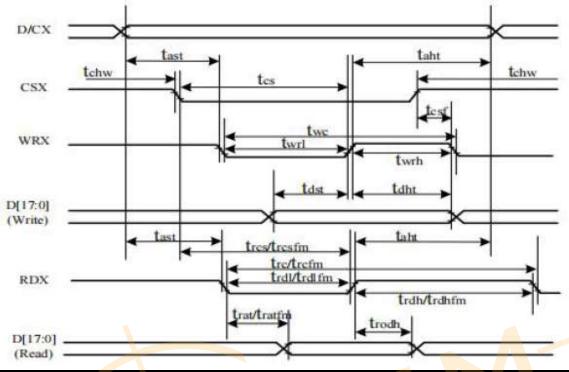
Note 2 : Ta = 25 °C

Note 3: Brightness to be decreased to 50% of the initial value

Note 4: The single LED lamp case

6.AC Characteristics

6.1. Display Parallel 18/16/9/8-bit Interface Timing Characteristics (8080)



Signal	Symbol	Parameter	min	max	Unit	Des cription
DCX	tast	Address setup time	0		ns	DE
DCX	taht	Address hold time(Write/Read)	0		ns	
	tchw	CSX "H" pulse width	0		ns	
	tcs	Chip Select setup time(Write)	15		ns	
CSX	trcs	Chip Select setup time(Read ID)	45		ns	
	trcsfm	Chip Select setup time(Read FM)	355		ns	
	tcsf	Chip Select Wait time (Write/Read)	10		ns	
	twc	Write Cycle	66		ns	
WRX	twrh	Write Control pulse H duration	15		ns	
	twrl	Write Control pulse L duration	15		ns	
	trcfm	Read Cycle (FM)	380		ns	
RDX(FM)	trdhfm	Read Control H duration(FM)	180		ns	
	trdlfm	Read Control L duration(FM)	200		ns	
	trc	Read Cycle (ID)	160		ns	
RDX(ID)	trdh	Read Control H pulse duration	90		ns	
	trdl	Read Control L pulse duration	70		ns	
D[17:0]	tdst	Write data setup time	10		ns	For maximum
D[I5:0]	tdht	Write data hold time	10		ns	CL=30pF
D[0.0]	trat	Read access time	-	40	ns	
D[8:0] D[7:0]	tratfm	Read access time	-	340	ns	For minimum CL=8pF
ره. ۱٫۰	trod	Read output disable time	20	80	ns	OL-Opi

Note: Ta = 25 °C,IOVCC=1.65V to 3.3V,VCC=2.5V to 3.3V,GND=0V Figure 1

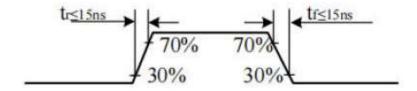
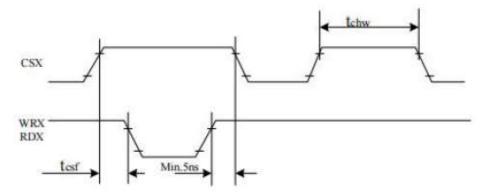


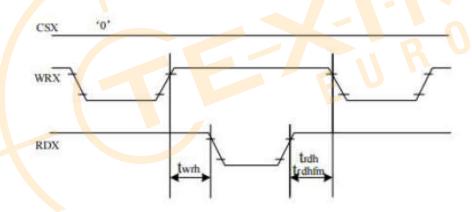
Figure 2



Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

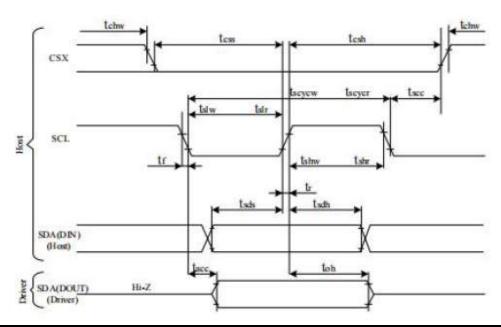
Write to read or read to write timings:

Figure 3



Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

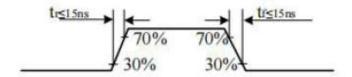
6.2. Display Serial Interface Timing Characteristics (3-line SPI system) Figure 4



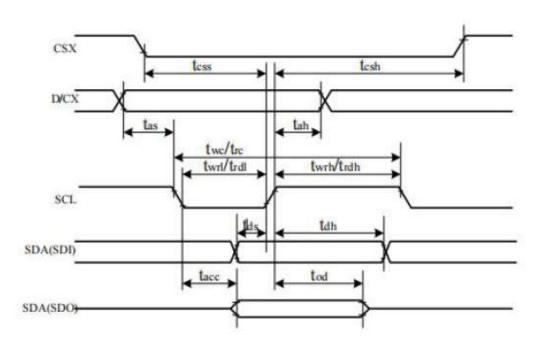
Signal	Symbol	Parameter	min	max	Unit	Description
	tscycw	Serial Clock Cycle (Write)	10		ns	
	tshw	SCL "H" Pulse Width (Write)	5		ns	
SCL	tslw	SCL "L" Pulse Width (Write)	5		ns	
SCL	tscycr	Serial Clock Cycle (Read)	150		ns	
	tshr	SCL "H" Pulse Width (Read)	60		ns	
	tslr	SCL "L" Pulse Width (Read)	60		ns	
SDA/S <mark>D</mark> I	tsds	Da <mark>ta</mark> setup time (Write)	5		ns	
(Inpu <mark>t)</mark>	tsdh	Data hold time (Write)	5		ns	
SDA/SDO(Output)	tacc	Access time (Read)	10		ns	
	tscc	SCL-CSX	10		ns	
CCV	tchw	CSX "H" Pulse Width	10		ns	
CSX	tcss	CSV SCI Time	20		ns	
	tcsh	CSX-SCL Time			ns	

Note: Ta = 25 °C,IOVCC=I.65Vto3.3V, VCC=2.5V to 3.3V. GND=0V

Figure5



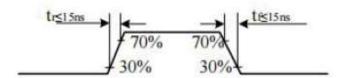
6.3. Display Serial Interface Timing Characteristics (4-line SPI system) Figure6



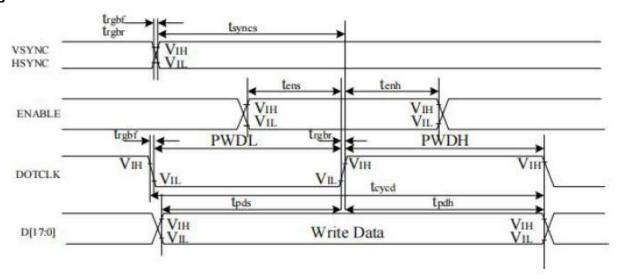
Signal	Symbol	Parameter	min	Max	unit	Description
CSX	tcss	Chip select time (Write)	20		ns	
03/	tcsh	Chip select hold time (Read)	40		ns	2
	twc	Serial Clock Cycle (Write)	10		ns	
	twrh	SCL "H" Pulse Width (Write)	5		ns	
SCL	twrl	SCL "L" Pulse Width (Write)	5		ns	
	trc	Seria <mark>l C</mark> lock Cy <mark>cle (R</mark> ead)	150		ns	
	trdh	SCL "H" Pulse Width (Read)	60		ns	
	trdl	SCL"L" Pulse Width (Read)	60		ns	
D/CX	tas	D/CX setup time	10		ns	
	tah	D/CX hold time (Write/Read)	10		ns	
SDA/SDI	tds	Data setup time (Write)	5		ns	
(Input)	tdh	Data hold time (Write)	5		ns	
SDA/SDO (Output)	tacc	Access time (Read)	10		ns	

Note: Ta =25 °C, IOVCC=I.65V to 3.3V. VCC=2.5V to 3.3V, GND=0V

Figure7

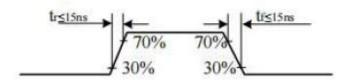


6.4. Parallel 18/16/6-bit RGB Interface Timing Characteristics Figure8

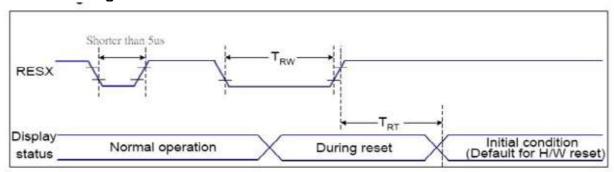


Signal	Symbol Parameter		min	Max	unit	Description
VSYNC/	tsyncs	VSYNC/HSYNC setup time	15		ns	
HSYNC	tsynch	VSYNC/HSYNC hold time	15		ns	
DE	tens	DE setup time	15		ns	
DE	tenh	DE hold time	15		ns	
D[17:0]	tpos	Data setup time	15		ns	18/16-bit bus
D[17:0]	tpdh	Date hold time	15		ns	RGB interface mode
	PWDH	DOTCLK high-level period	15		ns	mode
	PWDL	DOTCLK low- level period	15		ns	
DOTCLK	tcycd	DOTCLK cycle time	100		ns	
	trgbr.trgbf	DOTCLK ,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC/	tsyncs	VSYNC/HSYNC setup time	15		ns	
HSYNC	tsynch	VSYNC/HSYNC hold time	15		ns	
DE	tens	DE setup time	15		ns	
	tenh	DE hold time	15		n\$	
D[47:0]	tpos	Data setup time	15		ns	6-bit bus RGB
D[17:0]	tpdh	Dale hold time	15		ns	interface mode
DOTCLK	PWDH	DOTCLK high-level pulse period	15		ns	
	PWDL	DOTCLK low -level pulse period	15		ns	
	tcycd DOTCLK cycle time		100		ns	
	trgbr.trgbf	DOTCLK ,HSYNC,VSYNC rise/fall time	-	15	ns	

Note: Ta =25 °C, IOVCC=I.65V to 3.3V. VCC=2.5V to 3.3V, GND=0V



6.5. Reset Timing Characteristics



IOVCC=1.65 to 3.3V. VCC=2.4 to 3.3V. GND=0V. Ta= 25 °C

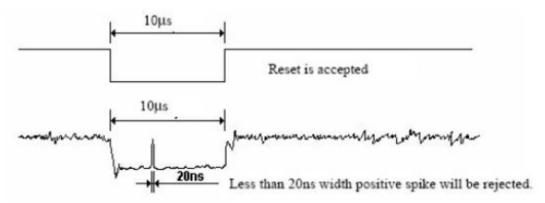
Related Pins	Symbol	Parameter	MIN	MAX	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TRT Reset cancel	Deartement	-	5 (Note 1,5)	ms
			120 (Note 1,6, 7)	ms	

Notes:

- 1.The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
- 2.Spike due to an elect<mark>r</mark>ostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out -mode. The display remains the blank state in Sleep In -mode.) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode
- 6. When Reset applied during Sleep Out Mode.
- 7.It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



7.Optical Characteristics

Item		Symbol	Condition.	Min	Тур.	Max.	Unit	Remark
Response time		Tr+ Tf	θ=0°、Φ=0°	-	30	35	.ms	Note 3
Contrast ratio		CR	At optimized viewing angle	500	700	-	-	Note 4
Color	White	Wx	θ=0°、Ф=0	0.214	0.264	0.314	-	Note
Chromaticity	vvnite	Wy		0.245	0.295	0.345	-	2,5,6
Viewing angle	Hor.	ΘR	- CR≧10	80	85	-	Dog	Note 1
Viewing angle (Gray Scale		ΘL		80	85	-		
Inversion		ΦТ		80	85	-	Deg.	Note 1
Direction)		ФВ		80	85	-		
Brightness		-	-	430	500	-	cd/m²	Center of display
Uniformity		(U)	-	75	_	_	%	Note 5

Ta=25±2°C,

Note 1: Definition of viewing angle range

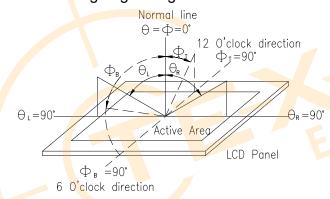


Fig. 7.1. Definition of viewing angle

Note 2: Test equipment setup:

After stabilizing and leaving the panel alone at a driven temperature for 10 minutes, the measurement should be executed. Measurement should be executed in a stable, windless, and dark room. Optical specifications are measured by Topcon BM-7orBM-5 luminance meter 1.0° field of view at a distance of 50cm and normal direction.

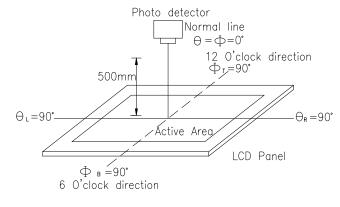
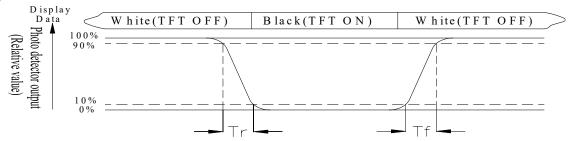


Fig. 7.2. Optical measurement system setup

Note 3: Definition of Response time:

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time, Tr, is the time between photo detector output intensity changed from 90%to 10%. And fall time, Tf, is the time between photo detector output intensity changed from 10%to 90%



Note 4: Definition of contrast ratio:

The contrast ratio is defined as the following expression.

Contrast ratio (CR) = Luminance measured when LCD on the "White" state

Luminance measured when LCD on the "Black" state

Note 5: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (reference the picture in below). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity (U) = Lmin/Lmax x100%

L = Active area length

W = Active area width

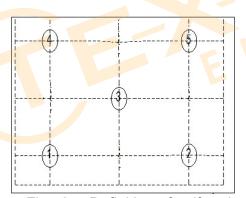


Fig7.3. Definition of uniformity

Note 6: Definition of color chromaticity (CIE 1931) Color coordinates measured at the center point of LCD

Note 7: Measured at the center area of the panel when all the input terminals of LCD panel are electrically opened.

8.Interface

8.1. LCM PIN Definition

Pin No	Symbol	Function	I/O
1	VLED+	Anode pin of backlight	Р
2	VLED*	Cathode pin of backlight	Р
3	GND	Ground.	Р
4	GND	Ground.	Р
5	VCC	Supply voltage (2.5-3.3V).	Р
6	IOVCC	Supply voltage (1.65-3.3V).	Р
7	RESET	This signal will reset the device and must be applied to properly initialize the chip.	I
8	WR(SPI-RS)	-Write enable in MCU parallel interface. Display data/command selection pin in 4-line serial interface. Second Data lane in 2 data lane serial interfaceIf not used, please fix this pin at IOVCC or GND.	I
9	CS	Chip select input pin ("Low" enable ,CSX). Fix this pin at IOVCC or GND when not in use.	I
10	RS(SPI-SCL)	-Display data/command selection pin in parallel interface.(D/CX) -This pin is used to be serial interface clock. (SCL) DC='1': display data or parameter. DC='0': command dataIf not used, please fix this pin at IOVCC or GND.	I
11	RD	Serves as a read signal and MCU read data at the rising edge. Fix this pin at IOVCC or GND when not in use.	I
12	PCLK	Dot clock signal for RGB interface operation. (DOTCLK) Fix this pin at IOVCC or GND when not in use.	I
13	DE	Data enable signal for RGB interface operation. (ENABLE) fix this pin at IOVCC or GND when not in use.	I
14	VSYNC	Frame synchronizing signal for RGB interface operation. fix this pin at IOVCC or GND when not in use.	I
15	HSYNC	Line synchronizing signal for RGB interface operation. fix this pin at IOVCC or GND when not in use.	I
16	TE	Tearing effect output pin to synchronize MPU to frame writing, activated by S/W command. When this pin is not activated, this pin is low. If not used, open this pin.	I
17	NC	No connection	0
18	SDA	The data is latched on the rising edge of the SCL signal. If not used, please fix this pin at IOVCC or GND level	I/O

19-36	DB17-DB0	18-bit parallel bi-directional data bus for MCU system and RGB interface mode . 18-bit RGB DB0:BLUE LSBDB5:BLUE MSB; DB6:GREEN LSBDB11:GREEN,MSB; DB12:RED LSBDB17:RED MSB. 16-bit RGB: DB1:BLUE LSBDB5:BLUE MSB; DB6:GREEN LSBDB11:GREEN,MSB; DB6:GREEN LSBDB17:RED MSB. mode Fix to GND level when not in use	I/O
37	IM0	MPU Parallel interface bus and serial interface select If use RGB Interface	
38	IM1	must select serial interface.	ı
39	IM3	Fix this pin at IOVCC and GND.	

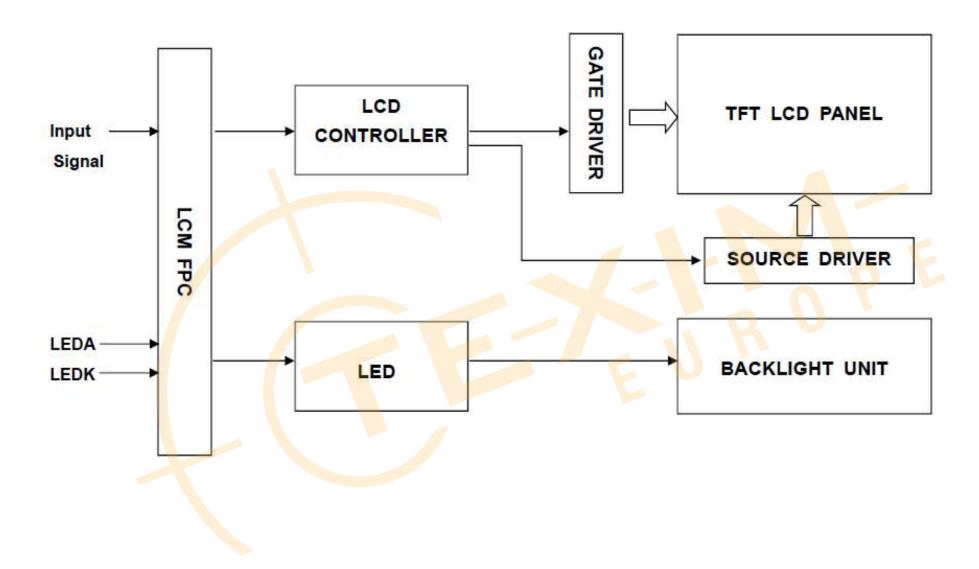
MCU interface SET for IM PINS

IM3	IM1	IMO	Interface Type	DB Pin in use	
L	L	L	8080 MCU 8-bit bus interface	DB7-DB0	
L	Н	L	8080 MCU 16-bit bus interface	DB15- DB0	
L	L	Н	8080 MCU 9-bit bus interface DB8- DB0		
L	Н	Н	8080 MCU 18-bit bus interface	DB17- DB0	
Н		Н	3-wire 9-bit data serial interface	SDA:In/Out	
П	_		2 d <mark>ata lin</mark> e serial interface	SDA:In/Out,DCX:In	
Н	Н	Н	4-wire 8-bit data serial interface	SDA:In/Out	

Note:

^{1.}Input Pin if not use, please connect to GND.
Output Pin if not use, please empty
2.If use RGB interface must select serial interface

9.Block Diagram



10.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test							
Test Item	Content of Test	Test Condition	Note				
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 96hrs	2				
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 96hrs	1,2				
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 96hrs	2				
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 96hrs	1,2				
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max	60°C,90%RH 96hrs	1,2				
Thermal shock resistance	The sample should be allowed stand the following 20 cycles of storage -10°C 25°C 60°C 30min 5min 30min 1 cycle	-10°C/60°C 20 cycles	2				
Vibration te <mark>s</mark> t	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3				
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±TBD(contact), ± TBD V(air), RS=330Ω CS=150pF 5 times	4				

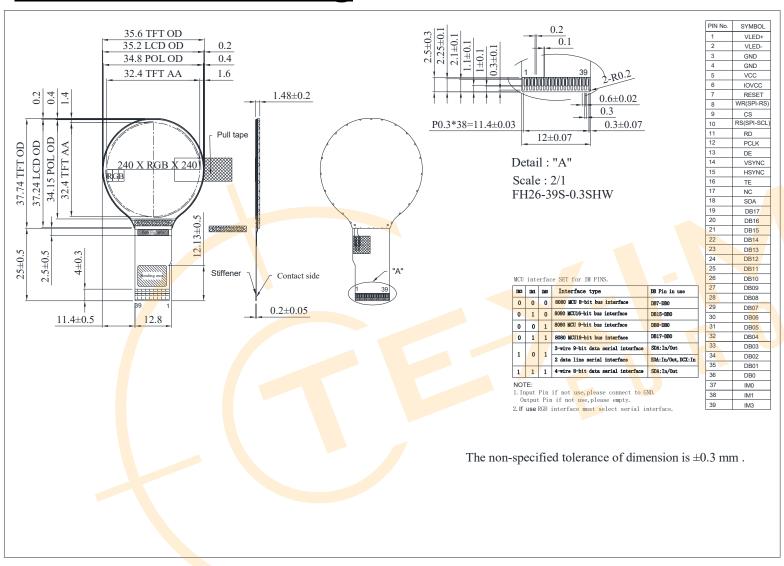
Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Note4: Endurance test applying the electric stress to the finished product housing

11.Contour Drawing



12.Initial Code For Reference

{

```
void GC9A01_initial(void)
    Write_Command(0xFE);
    Write_Command(0xEF);
    Write_Command(0xEB);
    Write_Data(0x14);
    Write_Command(0x84);
    Write_Data(0x60);
    Write_Command(0x85);
    Write Data(0xFF);
    Write_Command(0x86);
    Write_Data(0xFF);
    Write Command(0x87);
    Write_Data(0xFF);
    Write_Command(0x8E);
    Write_Data(0xFF);
    Write_Command(0x8F);
    Write_Data(0xFF);
    Write Command(0x88);
    Write_Data(0x0A);
    Write_Command(0x89);
    Write_Data(0x23);
```

```
Write Command(0x8B);
Write_Data(0x80);
Write_Command(0x8C);
Write_Data(0x01);
Write_Command(0x8D);
Write_Data(0x03);
Write_Command(0xB5);
Write_Data(0x10);
Write_Data(0x10);
Write Command(0xB6);
Write_Data(0x00);
Write_Data(0x00);
Write_Command(0x36);
Write Data(0x48);
Write_Command(0x3A);
Write_Data(0x05);
Write_Command(0x90);
Write_Data(0x08);
Write_Data(0x08);
Write Data(0x08);
Write_Data(0x08);
Write_Command(0xBA);
Write_Data(0x0A);
Write Command(0xBD);
```

```
Write_Data(0x06);
Write Command(0xBC);
Write_Data(0x00);
Write Command(0xFF);
Write_Data(0x60);
Write_Data(0x01);
Write_Data(0x04);
Write_Command(0xC3);
Write_Data(0x0C);
Write Command(0xC4);
Write_Data(0x0C);
Write_Command(0xC9);
Write_Data(0x22);
Write Command(0xBE);
Write Data(0x11);
Write Command(0xE1);
Write_Data(0x10);
Write_Data(0x0E);
Write Command(0xDF);
Write Data(0x21);
Write_Data(0x0C);
Write_Data(0x02);
Write_Command(0xF0);
Write_Data(0x45);
Write Data(0x09);
```

```
Write_Data(0x08);
Write Data(0x08);
Write_Data(0x26);
Write_Data(0x2A);
Write Command(0xF1);
Write_Data(0x43);
Write_Data(0x70);
Write_Data(0x72);
Write_Data(0x36);
Write_Data(0x37);
Write_Data(0x6F);
Write_Command(0xF2);
Write_Data(0x45);
Write_Data(0x09);
Write_Data(0x08);
Write_Data(0x08);
Write_Data(0x26);
Write_Data(0x2A);
Write_Command(0xF3);
Write_Data(0x43);
Write_Data(0x70);
Write_Data(0x72);
Write_Data(0x36);
Write_Data(0x37);
Write Data(0x6F);
Write_Command(0xED);
Write_Data(0x1B);
Write_Data(0x0B);
Write Command(0xAE);
```

```
Write_Data(0x77);
Write_Command(0xCD);
Write_Data(0x63);
Write Command(0x70);
Write_Data(0x07);
Write_Data(0x07);
Write_Data(0x04);
Write_Data(0x0F);
Write_Data(0x0F);
Write_Data(0x09);
Write Data(0x07);
Write_Data(0x08);
Write_Data(0x03);
Write_Command(0xE8);
Write_Data(0x24);
Write Command(0xE9);
Write Data(0x08);
Write_Command(0x60);
Write_Data(0x38);
Write_Data(0x14);
Write_Data(0x2D);
Write Data(0x6D);
Write Data(0x38);
Write_Data(0x16);
Write_Data(0x2D);
Write_Data(0x6D);
Write_Command(0x61);
Write Data(0x3A);
```

```
Write_Data(0x02);
Write Data(0x6D);
Write_Data(0x2D);
Write_Data(0xFA);
Write_Data(0x0F);
Write_Data(0x6D);
Write_Data(0x6D);
Write_Command(0x62);
Write_Data(0x38);
Write_Data(0x18);
Write_Data(0x72);
Write Data(0x00);
Write_Data(0x2D);
Write_Data(0x6D);
Write_Data(0x38);
Write_Data(0x1C);
Write_Data(0x72);
Write Data(0x04);
Write Data(0x2D);
Write_Data(0x6D);
Write_Command(0x63);
Write_Data(0x7A);
Write_Data(0x1F);
Write Data(0x72);
Write_Data(0x0F);
Write_Data(0x6D);
Write_Data(0x6D);
Write_Command(0x66);
Write_Data(0xF4);
Write Data(0x00);
```

```
Write_Data(0xCD);
Write Data(0x02);
Write_Data(0x4C);
Write_Data(0x5D);
Write_Data(0xBA);
Write_Data(0x01);
Write_Data(0x00);
Write_Data(0x00);
Write_Command(0x67);
Write_Data(0x00);
Write_Data(0x2F);
Write Data(0x00);
Write_Data(0x00);
Write_Data(0x10);
Write_Data(0xAB);
Write_Data(0x91);
Write_Data(0x80);
Write_Data(0x20);
Write Data(0x98);
Write_Command(0x74);
Write_Data(0x10);
Write_Data(0x80);
Write_Data(0x80);
Write Data(0x00);
Write Data(0x00);
Write_Data(0x4E);
Write_Data(0x00);
Write_Command(0x98);
Write_Data(0x3E);
Write Data(0x07);
```

```
Write Command(0x99);
Write_Data(0x3E);
Write_Data(0x07);
Write_Command(0x35);
Write_Data(0x00);
Write_Command(0x21);
Write_Command(0x2a);
Write_Data(0x00);
Write_Data(0x00);
Write_Data(0x00);
Write_Data(0xEF);
Write_Command(0x2b);
Write_Data(0x00);
Write_Data(0x00);
Write_Data(0x00);
Write_Data(0xEF);
Write_Command(0x11);
delay1(200);
Write_Command(0x29);
delay1(200);
Write_Command(0x2C);
```

}

	Madula Numbar	le Estimate Fee	Degray 4
1 · <u>P</u>	anel Specification :		
1.	Panel Type:	□ Pass	□ NG ,
2.	View Direction:	□ Pass	□ NG ,
3.	Numbers of Dots:	□ Pass	□ NG ,
4.	View Area:	□ Pass	□ NG ,
5.	Active Area:	□ Pass	□ NG ,
6.	Operating	□ Pass	□ NG ,
7.	Storage Temperature :	□ Pass	□ NG ,
8.	Others:		
2 · <u>M</u>	<u>lechanical</u>		
1.	PCB Size :	□ Pass	□ NG ,
2.	Frame Size :	□ Pass	□ NG ,
3.	Material of Frame:	□ Pass	□ NG ,
4.	Connector Position:	□ Pass	□ NG ,
5.	Fix Hole Position:	□ Pass	□ NG ,
6.	Backlight Position:	□ Pass	□ NG ,
7.	Thickness of PCB:	□ Pass	□ NG ,
8.	Height of Frame to	□ Pass	□ NG ,
9.	Height of Module :	□ Pass	□ NG ,
10	. Oth <mark>e</mark> rs:	□ Pass	□ NG ,
3 \ <u>R</u>	elat <mark>ive Hole Size</mark> :		
1.	Pitch of Connector :	□ Pass	□ NG ,
2.	Hole size of Connector:	□ Pass	□ NG ,
3.	Mounting Hole size:	□ Pass	□ NG ,
4.	Mounting Hole Type:	□ Pass	□ NG ,
5.	Others:	□ Pass	□ NG ,
4 \ <u>B</u>	acklight Specification :		
1.	B/L Type:	□ Pass	□ NG ,
2.	B/L Color:	□ Pass	□ NG ,
3.	B/L Driving Voltage (Refer	ence for LED	□ Pass □ NG ,
4.	B/L Driving Current :	□ Pass	□ NG ,
5.	Brightness of B/L:	□ Pass	□ NG ,
6.	B/L Solder Method:	□ Pass	□ NG ,
7.	Others:	□ Pass	□ NG ,

>> Go to page 2 <<

	Winstar Module Number		Page: 2	
5、	Electronic Characteristics	of Module	:	•
1.	Input Voltage :	□ Pass	□ NG ,	
2.	Supply Current:	□ Pass	□ NG ,	
3.	Driving Voltage for LCD:	□ Pass	□ NG ,	
4.	Contrast for LCD:	□ Pass		
5.	B/L Driving Method:	□ Pass	□ NG ,	
6.	Negative Voltage Output:	□ Pass	□ NG ,	
7.	Interface Function:	□ Pass	□ NG ,	
8.	LCD Uniformity:	□ Pass	□ NG ,	
9.	ESD test :	□ Pass		
10.	Others:	□ Pass	□ NG ,	
6、	Summary:			
	signature :		Date: /	1 A P E

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